Device and Method for Stripping a Product Substrate Off a Carrier Substrate

Abstract

Device for stripping a product substrate off a carrier substrate connected to the product substrate by an bonding layer by means of a film frame, a flexible film which is connected to the film frame and which has an adhesive layer for holding the product substrate in a contacting surface section of the film, the film being connected to the film frame in an attachment section of the film which surrounds the contacting surface section, as well as a solvent reservoir formed by the film frame and the film, especially of variable volume, for holding the solvent for detaching the bonding layer, and the product substrate and the bonding layer can be accommodated in the solvent reservoir, and by delivery means for delivering the solvent into the solvent reservoir and by stripping means for stripping the product substrate off the carrier substrate.

Furthermore the invention relates to a method for stripping a product substrate off a carrier substrate by forming a solvent reservoir for holding solvent for detaching the bonding layer, which is formed by a film frame and a flexible film connected to the film frame, as well as by holding the product substrate and the bonding layer in the solvent reservoir, and by delivering solvent into the solvent reservoir and by detaching the product substrate from the carrier substrate.

Figure 4